

Amendments to the Specification

Please replace the paragraph beginning at page 7, line 10, with the following rewritten paragraph:

Fig. 2A is a perspective view illustrating prepreg sheet 3 thus manufactured. Fig. 2B is a sectional view of prepreg sheet 3 taken along line 2B-2B shown in Fig. 2A. Fig. 2C is a sectional view of prepreg sheet 3 taken along line 2C-2C shown in Fig. 2A. A variation of the thickness along a short-side direction shown in Fig. 2B is ~~larger~~ smaller than a variation of the thickness along the long-side direction shown in Fig. 2C.

Please replace the paragraph beginning at page 8, line 1, with the following rewritten paragraph:

According to the embodiment, MD 101 for manufacturing prepreg sheet 3 is orthogonal to MD 104 for sticking film ~~4 14~~ with respect to prepreg sheet 3.

Please replace the paragraph beginning at page 8, line 4, with the following rewritten paragraph:

Variations of the thickness, the heating temperature, and a pressure along MD 101 and MD 103 are small during the manufacturing of prepreg sheet 3 and the sticking of films ~~14 4~~. However, the variations are large along a direction orthogonal to MD 101 and MD 103. Therefore, if MD 101 matches MD 103 with respect to prepreg sheet 3 during the manufacturing of the prepreg sheet and the sticking of films ~~14 4~~, the variation of the thickness of sheet 3 remains until the circuit forming board is manufactured.

Please replace the paragraph beginning at page 8, line 11, with the following rewritten paragraph:

However, if MD 101 for manufacturing prepreg sheet 3 is orthogonal to MD 103 for sticking films ~~14~~ 4 with respect to prepreg sheet 3, the variations occurring in the both processes are cancelled, hence providing sheet 3 in laminated prepreg sheet 6 with a uniform thickness.

Please replace the paragraph beginning at page 8, line 27, with the following rewritten paragraph:

Then, as shown in Fig. 5D, films 4 are peeled off from sheet 6. Since just a small amount of resin component of films ~~14~~ 4 melting on the surfaces of sheet 3 to allow films 4 to be temporarily stuck onto sheet 3, films 4 can be peeled off easily. As shown in Fig. 5D, paste 8 projects from sheet 3 by thicknesses of films 4 after the peeling. Next, as shown in Fig. 5E, copper foils 9 are placed on upper and lower surfaces of sheet 3, and are then hot-pressed by a hot presser, such as a vacuum hot presser. The resin component of sheet 3 melts and undergoes molding and curing steps, and then, conductive paste 8 is compressed. As a result, copper foils 9 on both surfaces of sheet 3 are electrically connected to paste 8, as shown in Fig. 5F. Then, copper foils 9 are etched to have predetermined pattern for forming circuit 10, as shown in Fig. 5G, thus providing a double-sided circuit forming board.